

MDP6N60/MDF6N60

N-Channel MOSFET 600V, 6A, 1.4Ω

General Description

These N-channel MOSFET are produced using advanced Magnachip's MOSFET Technology, which provides low on-state resistance, high switching performance and excellent quality.

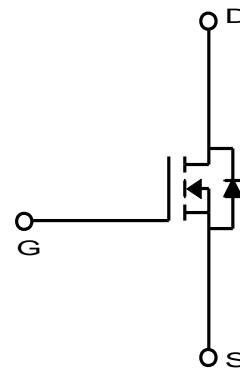
These devices are suitable device for SMPS, high Speed switching and general purpose applications.

Features

- $V_{DS} = 600V$
- $I_D = 6.0A$ @ $V_{GS} = 10V$
- $R_{DS(ON)} \leq 1.4\Omega$ @ $V_{GS} = 10V$

Applications

- Power Supply
- PFC
- High Current, High Speed Switching



Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristics	Symbol	MDP6N60	MDF6N60	Unit
Drain-Source Voltage	V_{DSS}	600		V
Gate-Source Voltage	V_{GSS}	± 30		V
Continuous Drain Current	I_D	6.0	6.0*	A
		3.8	3.8*	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	24	24*	A
Power Dissipation	P_D	131	37.9	W
		1.05	0.3	W/ $^\circ C$
Repetitive Avalanche Energy ⁽¹⁾	E_{AR}	13.1		mJ
Peak Diode Recovery $dv/dt^{(3)}$	dv/dt	4.5		V/ns
Single Pulse Avalanche Energy ⁽⁴⁾	E_{AS}	220		mJ
Junction and Storage Temperature Range	T_J, T_{stg}	-55~150		$^\circ C$
Mounting Torque		5		Kgf-cm

* I_D limited by maximum junction temperature

Thermal Characteristics

Characteristics	Symbol	MDP6N60	MDF6N60	Unit
Thermal Resistance, Junction-to-Ambient ⁽¹⁾	$R_{\theta JA}$	62.5	62.5	$^\circ C/W$
Thermal Resistance, Junction-to-Case ⁽¹⁾	$R_{\theta JC}$	0.95	3.3	

Ordering Information

Part Number	Temp. Range	Package	Packing	RoHS Status
MDP6N60TH	-55~150°C	TO-220	Tube	Halogen Free
MDF6N60TH	-55~150°C	TO-220F	Tube	Halogen Free

Electrical Characteristics (Ta =25°C)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = 250μA, V _{GS} = 0V	600	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	3.0	-	5.0	
Drain Cut-Off Current	I _{DSS}	V _{DS} = 600V, V _{GS} = 0V	-	-	1	μA
Gate Leakage Current	I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V	-	-	100	nA
Drain-Source ON Resistance	R _{Ds(ON)}	V _{GS} = 10V, I _D = 3.0A		1.2	1.4	Ω
Forward Transconductance	g _{fs}	V _{DS} = 30V, I _D = 3.0A	-	5	-	S
Dynamic Characteristics						
Total Gate Charge	Q _g	V _{DS} = 480V, I _D = 6.0A, V _{GS} = 10V ⁽³⁾	-	15.4	-	nC
Gate-Source Charge	Q _{gs}		-	4.4	-	
Gate-Drain Charge	Q _{gd}		-	5.9	-	
Input Capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = 0V, f = 1.0MHz	-	660	860	pF
Reverse Transfer Capacitance	C _{rss}		-	3.2	5	
Output Capacitance	C _{oss}		-	78	100	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 300V, I _D = 6A, R _G = 25Ω ⁽³⁾	-	14		ns
Rise Time	t _r		-	23.2		
Turn-Off Delay Time	t _{d(off)}		-	32.2		
Fall Time	t _f		-	21.2		
Drain-Source Body Diode Characteristics						
Maximum Continuous Drain to Source Diode Forward Current	I _S		-	6.0	-	A
Source-Drain Diode Forward Voltage	V _{SD}	I _S = 6.0A, V _{GS} = 0V	-		1.4	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = 6.0A, dI/dt = 100A/μs ⁽³⁾	-	275		ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	2.1		μC

Note :

1. Pulse width is based on R_{θJC} & R_{θJA} and the maximum allowed junction temperature of 150°C.
2. Pulse test: pulse width ≤300us, duty cycle≤2%, pulse width limited by junction temperature T_{J(MAX)}=150°C.
3. I_{SD} ≤6.0A, di/dt≤200A/us, V_{DD}=50V, R_g =25Ω, Starting T_J=25°C
4. L=8.7mH, I_{AS}=6.0A, V_{DD}=50V, R_g =25Ω, Starting T_J=25°C,



RoHS Compliant
HALOGEN-FREE

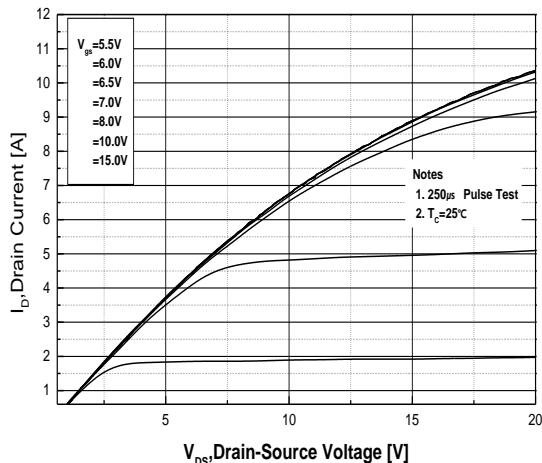


Fig.1 On-Region Characteristics

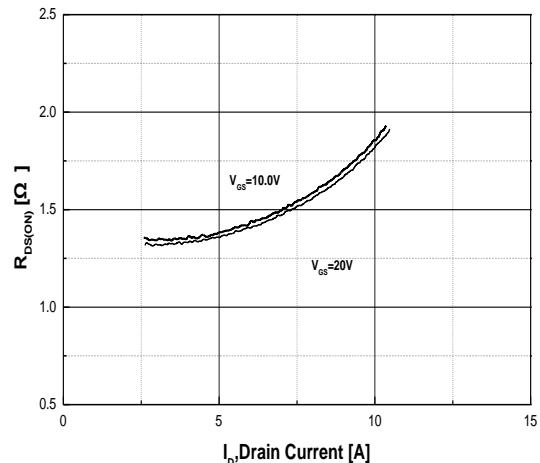


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

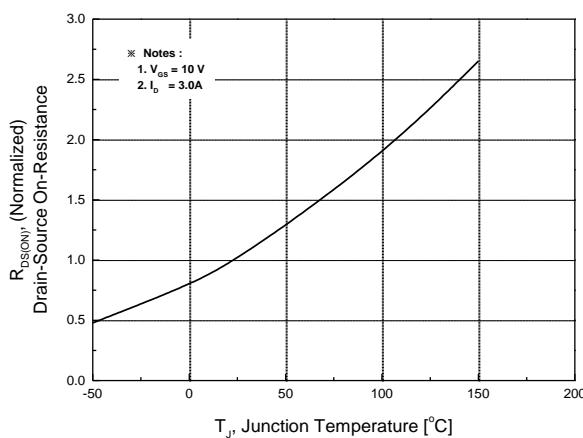


Fig.3 On-Resistance Variation with Temperature

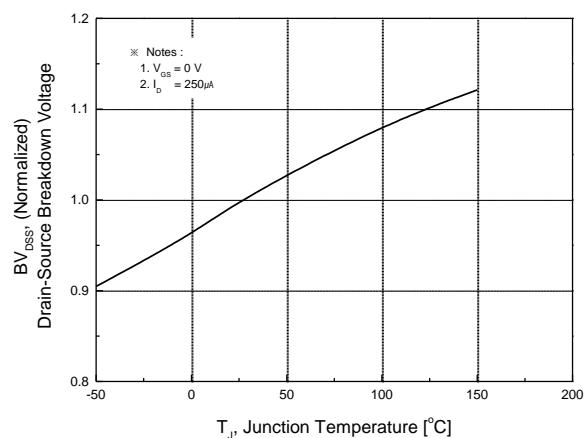


Fig.4 Breakdown Voltage Variation vs. Temperature

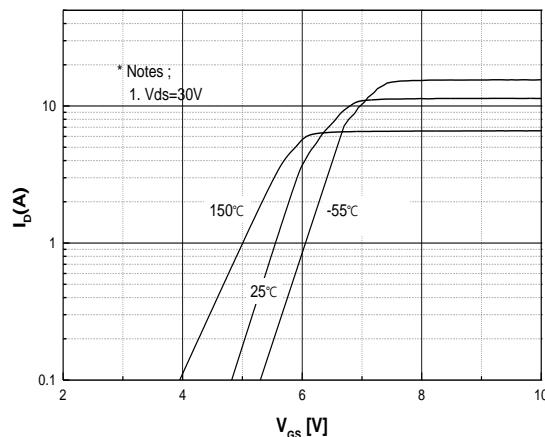


Fig.5 Transfer Characteristics

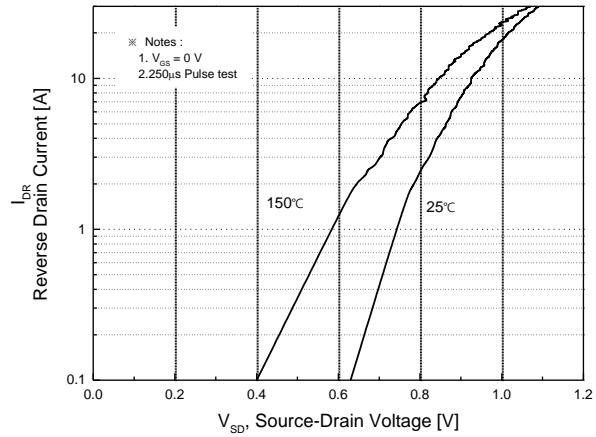


Fig.6 Body Diode Forward Voltage Variation with Source Current and Temperature

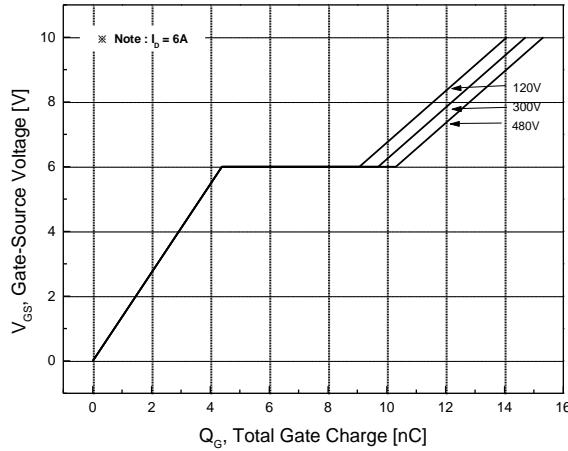


Fig.7 Gate Charge Characteristics

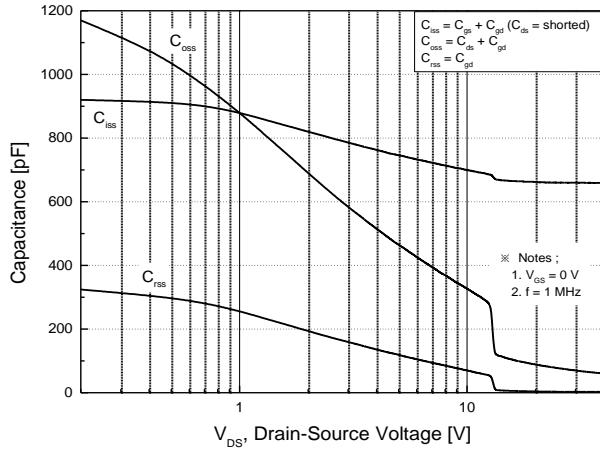
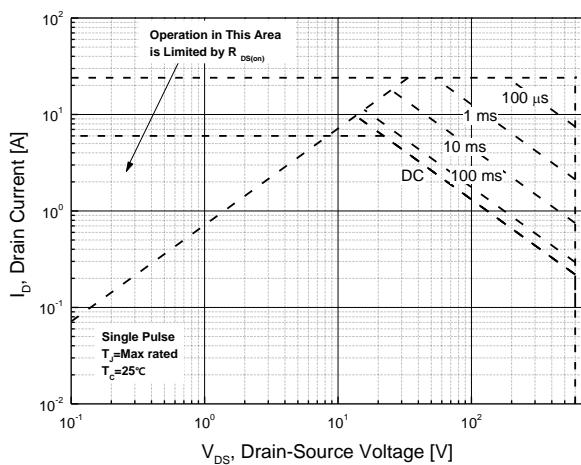
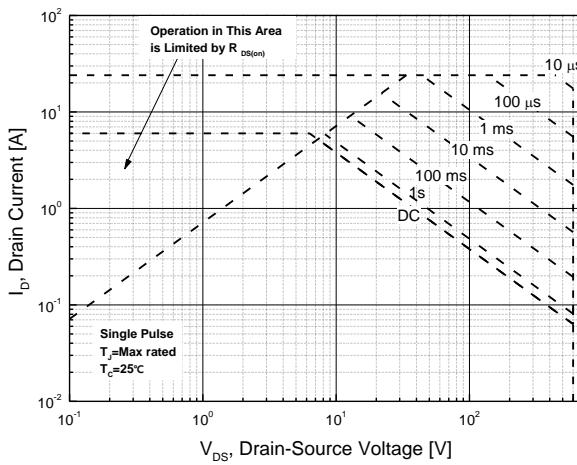


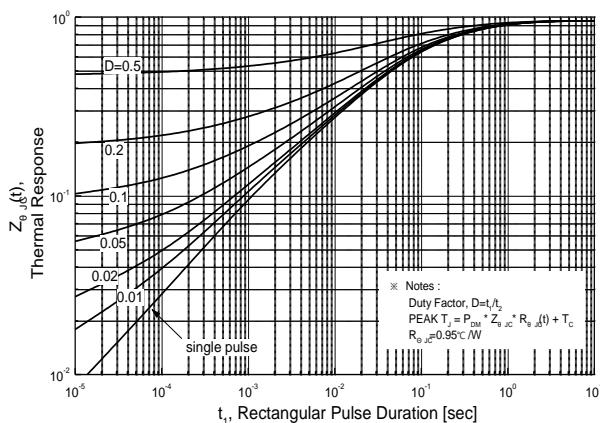
Fig.8 Capacitance Characteristics



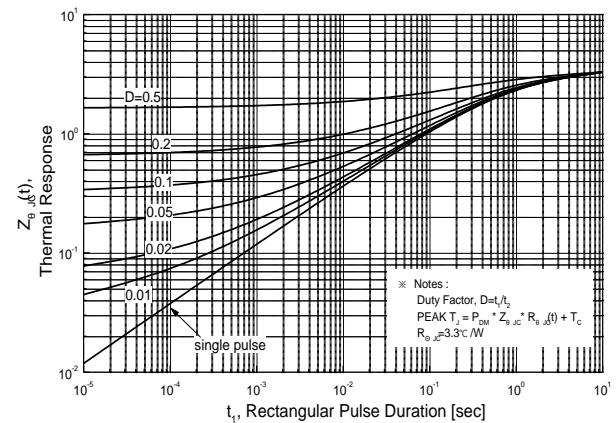
**Fig.9 Maximum Safe Operating Area
MDP6N60(TO-220)**



**Fig.10 Maximum Safe Operating Area
MDF6N60(TO-220F)**



**Fig.11 Transient Thermal Response Curve
MDP6N60(TO-220)**



**Fig.12 Transient Thermal Response Curve
MDF6N60(TO-220F)**

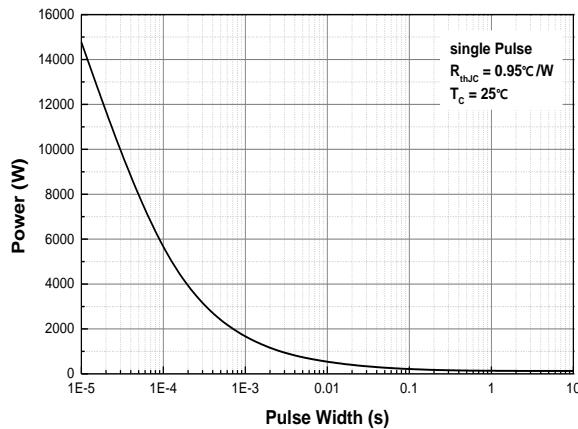


Fig.13 Single Pulse Maximum Power Dissipation MDP6N60(TO-220)

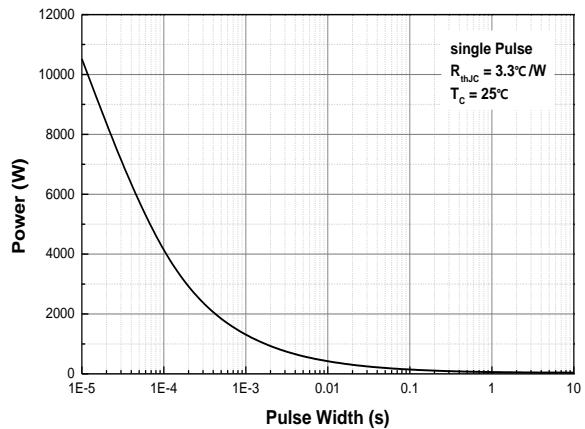


Fig.14 Single Pulse Maximum Power Dissipation MDF6N60(TO-220F)

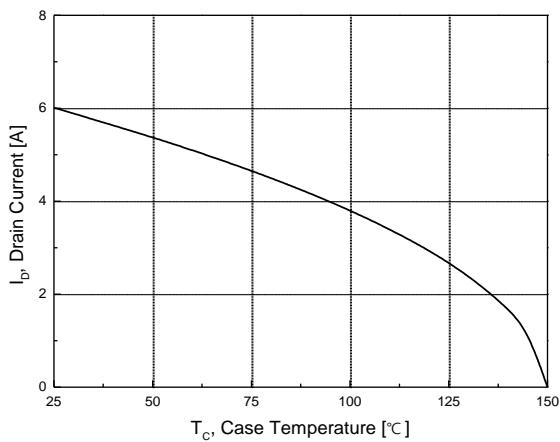
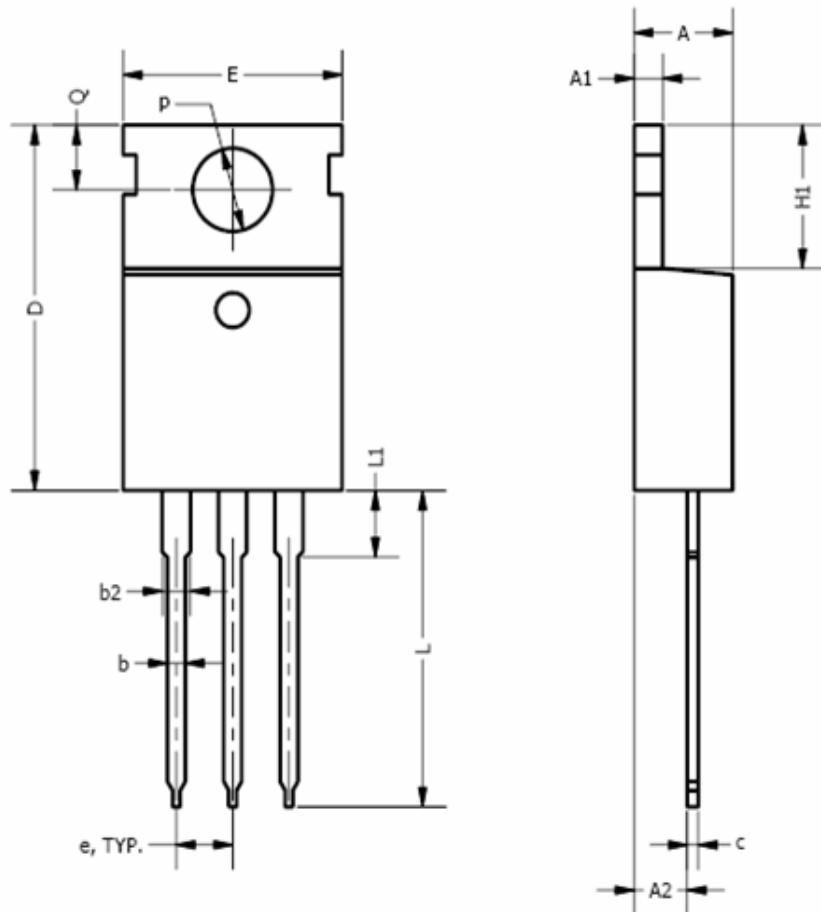


Fig.15 Maximum Drain Current vs. Case Temperature

Physical Dimensions

TO-220

Dimensions are in millimeters unless otherwise specified

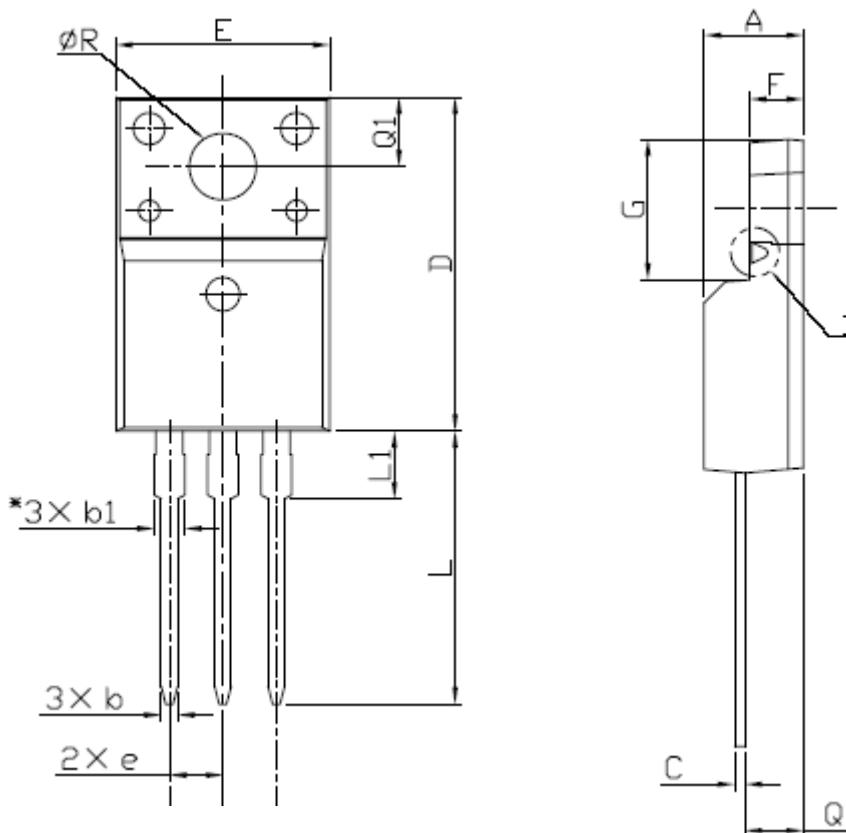


Symbol	Min	Nom	Max
A	3.56		4.83
A1	0.50		1.40
A2	2.03		2.92
b	0.38	0.69	1.02
b2	1.14	1.45	1.78
c	0.36		0.61
D	14.22		16.51
e	2.54 TYP		
E	9.65		10.67
H1	5.84		6.86
L	12.70		14.73
L1			6.35
φP	3.53		4.09
Q	2.54		3.43

Physical Dimensions

TO-220F

Dimensions are in millimeters unless otherwise specified



Symbol	Min	Nom	Max
A	4.50		4.93
b	0.63		0.91
b1	1.15		1.47
C	0.33		0.63
D	15.47		16.13
E	9.60		10.71
e		2.54	
F	2.34		2.84
G	6.48		6.90
L	12.24		13.72
L1	2.79		3.67
Q	2.52		2.96
Q1	3.10		3.50
ØR	3.00		3.55

DISCLAIMER:

The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. Seller's customers using or selling Seller's products for use in such applications do so at their own risk and agree to fully defend and indemnify Seller.

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